

**In the Claims:**

Please amend claims 1, 3, 5-9, 12-14, 16, 17, 19, 20, 23 and 26, cancel claim 4 without prejudice or disclaimer, and add new claims 30 and 31 to appear as indicated in the following listing, which replaces all prior versions.

1. (Currently amended) A high frequency component with a substrate constructed of a plurality of dielectric layers and, between them, electrode layers having conducting track structures, ~~in which the~~ substrate including a resonator element having at least one capacitive element and at least one inductive element ~~[[is]] formed, whereby~~ by at least one arrangement of opposed conducting track structures, the opposed conducting track structures being separated by a dielectric layer having a thickness that is smaller than the width of either of the opposed conducting track structures, is provided, these realizing simultaneously the at least one capacitive and inductive elements, whereby the dielectric layer having a dielectric constant and thickness selected such that the common-mode impedance and the push-pull impedance between the opposed ~~at least two opposing~~ conducting track structures ~~are adjusted to~~ differs by a factor of at least 2.
2. (Original) A high frequency component according to claim 1, characterized in that the conducting track structures are linked to each other at least at one site by a conductor or with fixed potentials.
3. (Currently amended) A high frequency component according to claim 1, characterized in that the common-mode impedance of and the push-pull impedance between the at least two opposing conducting track structures ~~are adjusted to~~ differ by a factor of at least 10.
4. (Cancelled).
5. (Currently amended) A high frequency component according to claim 1, characterized in that the thickness ~~[[d]]~~ of ~~[[a]]~~ the dielectric layer arranged between the opposed conducting track structures of the at least one arrangement is smaller than one

opposed conducting track structures of the at least one arrangement is smaller than one fifth of the width of either of the opposed conducting track structures.

6. (Currently amended) A high frequency component according to claim 1, characterized in that ~~[[a]]~~ the dielectric layer between the opposed conducting track structures of the at least one arrangement has an increased dielectric constant compared with surrounding dielectric layers.

7. (Currently amended) A high frequency component according to claim 1, characterized in that ~~[[a]]~~ the dielectric layer between the opposed conducting track structures of the at least one arrangement has a dielectric constant of greater than 5.

8. (Currently amended) A high frequency component according to claim 1, characterized in that ~~[[a]]~~ the dielectric layer between the opposed conducting track structures of the at least one arrangement has a dielectric constant of greater than 70.

9. (Currently amended) A high frequency component according to claim 1, ~~characterized in that layer is disposed between the opposed conducting tracks of the at least one arrangement, where the layer~~ wherein the dielectric layer between the opposed conducting track structures contains materials with barium-rare earth-titanium-perovskites, barium-strontium-titanates, bismuth pyrochlore structures, tantalum oxides, magnesium-aluminium-calcium-silicates, (calcium, strontium)-zirconates and/or magnesium titanates, also in combination with boron or lead silicate glasses.

10. (Original) A high frequency component according to claim 1, characterized in that the substrate is a ceramic laminate as a low temperature co-fired ceramics (LTCC) material or a high temperature co-fired ceramics (HTCC) material, an organic laminate, a semiconductor substrate or a substrate based on thin film technology.

11. (Previously presented) A high frequency component according to claim 1, characterized by a working frequency above 400 MHz.

12. (Currently amended) A high frequency component according to claim 1, characterized in that the conducting track width of one of the opposed conducting track structures of the at least one arrangement is larger than that of the other opposed ~~the~~ ~~opposing~~ conducting track structure by a factor of  $2k$ , where  $k$  is at least 70% of the sum of a layer offset  $v$  of the ~~opposing~~ opposed conducting track structures and half the thickness  $d$  of ~~[[a]]~~ the dielectric layer situated between the ~~opposing~~ opposed conducting track structures.

13. (Currently amended) A high frequency component according to claim 1, characterized in that the opposed conducting track structures of the at least one arrangement each includes two ~~on one electrode layer~~ has sections running in the same direction, and wherein the two sections of one of the opposed conducting track structures have and having a separation that is larger than a separation between the two sections of the other of the opposed conducting track structures of electrode in the opposing ~~conducting track structure~~ by a factor of  $2k$ , whereby  $k$  is at least 50% of the sum of a layer offset  $v$  of the opposed conducting track structures ~~one of the electrode layers~~ and half the thickness  $d$  of ~~[[a]]~~ the dielectric layer situated between the ~~electrode layers~~ opposed conducting track structures.

14. (Currently amended) A high frequency component according to claim 1, characterized in that the opposed ~~opposing~~ conducting tracks of the at least one arrangement are coupled by a bridge or by a common conducting member.

15. (Previously presented) A high frequency component according to claim 14, characterized in that the bridge or the conducting member is a connection between two of the electrode layers.

16. (Currently amended) A resonator in a high frequency component according to claim 1, characterized in that each of the opposed conducting track structures of the ~~[[in]]~~ at least one arrangement includes a start and an end defined by a current path ~~of opposed~~

~~conducting tracks, wherein the~~ [[one]] start of one of the ~~opposing~~ opposed conducting tracks is placed at the same potential as ~~the~~ [[one]] end of the other of the ~~opposing~~ opposed conducting tracks ~~or the one start is connected to the one end via a conductor,~~ the remaining end of the one of the opposed conducting tracks and the remaining start of the other of the opposed conducting tracks being unconnected.

17. (Currently amended) A resonator in a high frequency component according to claim 16, characterized in that the start of the one opposed conducting track is connected to the end of the other opposed conducting track via a connecting conductor, the connecting conductor being ~~is designed~~ as a non-overlapping extension of the opposed conducting tracks ~~of the opposed conductor structures~~ and/or [[as]] at least one lead-through through at least one insulating layer disposed between the opposed conducting tracks.

18. (Previously presented) A resonator in a high frequency component claim 1, characterized in that in the at least one arrangement of opposed conducting tracks, one start of one of the opposed conducting track and one end of the other of the opposed conducting tracks are connected to a fixed potential.

19. (Currently amended) A resonator according to claim 16, characterized in that [[one]] the remaining unconnected end of the one of the opposed conducting tracks is placed at a fixed potential.

20. (Currently amended) A resonator according to claim 16, characterized in that ~~at least one~~ the remaining unconnected end of the one of the opposed conducting tracks is extended with a conducting track extension and/or connected to earth with a capacitor.

21. (Previously presented) A resonator according to claim 16, characterized in that on at least one side of the opposed conducting track structures, an earth surface is provided.

22. (Original) A resonator according to claim 16, characterized in that the opposed

conducting track structures are surrounded by magnetic materials.

23. (Currently amended) A filter with at least one resonator according to claim 16, whereby the input and output of signals and the coupling to the at least one resonator ~~between the resonators~~ takes place directly via a ~~conducting track connected~~ connection to ~~[[a]]~~ the opposed conducting track structures, inductively through the conducting tracks running parallel in places and/or capacitively via a capacitor.

24. (Previously presented) A filter with least two resonators according to claim 16, whereby at least one coupling between the at least two resonators is generated through a common conducting track member connected to earth.

25. (Original) A balancing transformer (balun) having at least one resonator according to claim 16, whereby the input of signals takes place symmetrically and the output takes place asymmetrically.

26. (Currently amended) An adaptor network having at least one resonator according to claim 16, whereby the impedance of couplings between the opposed conducting track structures is determined by the positioning of the couplings.

27. (Original) A network with at least one resonator according to claim 16, which performs the function of a filter, a balancing transformer and/or of an adaptor network.

28. (Original) A high frequency module with at least one of the components claimed in claim 1.

29. (Original) A high frequency module according to claim 28, which performs the function of a transmitting and receiving module.

30. (New) The high frequency component according to claim 1, wherein the resonator element has a conductor length that is less than a quarter wavelength for working frequencies above 400 MHz.

31. (New) The high frequency component according to claim 1, wherein the dielectric layer has a thickness of 25  $\mu\text{m}$  or less.